α		06-26-199	98			
6-12-4	SON-1338			TEET	U.S. DEPARTMENT OF COMMER	
7	1007475		24			
1	To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.					
	1. Name of conveying party(ies) Koichi TAKEUCHI Additional name(s) of conveying party(ies) attached No 3. Nature of conveyance:		2. Name and address of receiving party(ies) Name: SONY CORPORATION			
NRD			Internal Addre	ss:	3C51	
/			Street Address: 7-35 KITASHINAGAWA 6-CHOME SHINAGAWA-KU			
	⊠ Assignment □ Merger	r	City: TOKYO), JAPAN		
	☐ Security Agreement ☐ Change	e of Name	Additional nan	ne(s) & address(es) attach	ed □ Yes ⊠ No	
	Other					
	Execution Date: June 8, 1998		Mark - Jan 18 18 18 18 18 18 18 18 18 18 18 18 18	and the second s		
	4. Application number(s) or patent number(s):					
	If the document is being filed together with a new application, the execution date of the application is June 8, 1998					
	Additional numbers attached No					
	5. Name and address of party to whom corresp document should be mailed:	ondence concerning	6. Total numb	per of applications and pat	ents involved: 1	
	Name: Ronald P. Kananen, Esc	q.	7. Total fee (3	37 CFR 3.41)	\$ 40.00	

06/25/1998 JSHABAZZ 00000201 180013 09095926 40.00 CH

Ronald P. Kananen

Name of Person Signing

Street Address:

document.

01 FC:581

City: Washington, D.C.

DO NOT USE THIS SPACE 9. Statement and signature.

Internal Address: RADER, FISHMAN & GRAUER

1233 20th Street, NW

Zip: 20036

Suite 501

18-0013

(Attach duplicate copy of this page if paying by deposit account)

June 12, 1998

Total number of pages comprising cover sheet 1

Enclosed

8. Deposit account number:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original

Signature

Docket Number: SON-1338

ASSIGN	MENT
whereas, I, as a below named inventor, residing only one name is listed below) or a joint inventor (if plural names METHOD OF MAKING MASK PATTERN, APPAR MASK PATTERN AND APPARATUS FOR MAKING or which application for Letters Patent of the United States of Ame and address;	ATUS FOR MAKING
AND WHEREAS, Sony Corporation, a Japane Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) said application disclosing the invention and in, to and under any therefor in the United States and in any and all foreign countries;	se corporation with offices at 7-35 Kitashinagawa 6-Chome, is desirous of acquiring all interest in, to and under said invention, Letters Patent or similar legal protection which may be granted
NOW THEREFORE, in consideration of the sum the receipt and sufficiency of which are hereby acknowledged, I, as hereby assign, sell and transfer unto the said ASSIGNEE, its success interest in the said invention, said application, including any division Patent of the United States, and countries foreign thereto, which may rights and/or convention rights under the International Convention for Relating to Patents, Designs and Industrial Models, and any other is adheres, and to any other benefits accruing or to accrue to me with patents in the United States and countries foreign thereto, and I hereb said United States Letters Patent to said ASSIGNEE, as the assigned	sors, assigns, and legal representatives, the entire right, title and one and continuations thereof, and in and to any and all Letters be granted for said invention, and in and to any and all priority the Protection of Industrial Property, Inter-American Convention international agreements to which the United States of American respect to the filing of applications for patents or securing of y authorize and request the Commissioner of Patents to issue the
And I further agree to execute all necessary or desirable a ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and without further remuneration, in order to perfect title in said applications and Letters Patent of the United States and countries fo	invention, modifications, and improvements in said invention,
And I further agree to properly execute and deliver and with papers for application for foreign patents, for filing subdivisions of reissues of any Letters Patent which may be granted for my aforesaid prepare at its own expense;	out further remuneration, such necessary or desirable and lawful said application for patent, and or, for obtaining any reissue or invention, as the ASSIGNEE thereof shall hereafter require and
And I further agree that ASSIGNEE will, upon its request relating to said application, said invention and said Letters Patent as accessible to me and will testify as to the same in any interference of	, be provided promptly with all pertinent facts and documents and legal equivalents in foreign countries as may be known and or litigation related thereto;
And I hereby covenant that no assignment, sale, agreement awould conflict with this assignment and sale.	or encumbrance has been or will be made or entered into which
And I hereby authorize and request my attorney(s) of record his application in the spaces that follow: Serial Number:	in this application to insert the serial number and filing date of
This assignment executed on the dates indicated below.	
KOICHI TAKEUCHI	Execution date of U.S. Patent Application
Name of first or sole inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of first or sole inventor	
Karchi Inkeroni	Jun. 8 1978 Date of this assignment
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 9256 FRAME: 0651